

ABSTRACT OF THE DISCLOSURE

A resin sealed IC has a plurality of external terminals. A metal thin film made of a Sn-Bi alloy is formed in direct contact with the surface of a base member of each external terminal. A Bi content in the Sn-Bi alloy layer is within a range of 0.5 to 6.0 wt%. Further, the Sn-Bi alloy layer has a single-layer plating structure, and the film thickness is within a range of 10 to 25 MIC.